

SN54AHC174, SN74AHC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR

SCLS425F – JUNE 1998 – REVISED FEBRUARY 2002

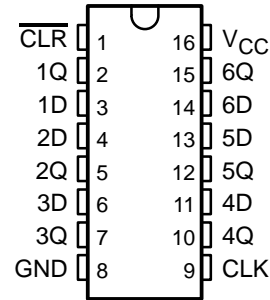
- Operating Range 2-V to 5.5-V V_{CC}
- Contain Six Flip-Flops With Single-Rail Outputs
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description

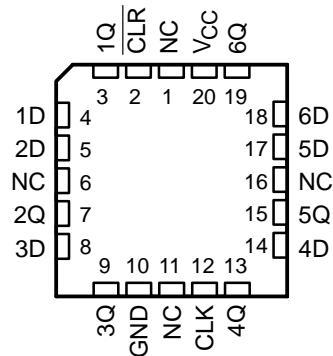
The 'AHC174 devices are positive-edge-triggered D-type flip-flops with a direct clear (CLR) input and are designed for 2-V to 5.5-V V_{CC} operation.

Information at the data (D) inputs that meets the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

SN54AHC174 ... J OR W PACKAGE
SN74AHC174 ... D, DB, DGV, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHC174 ... FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

| T_A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|-------------|---------------|-----------------------|------------------|
| –40°C to 85°C | PDIP – N | Tube | SN74AHC174N | SN74AHC174N |
| | SOIC – D | Tube | SN74AHC174D | AHC174 |
| | | Tape and reel | SN74AHC174DR | |
| | SOP – NS | Tube | SN74AHC174NSR | AHC174 |
| | SSOP – DB | Tape and reel | SN74AHC174DBR | HA174 |
| | TSSOP – PW | Tape and reel | SN74AHC174PWR | HA174 |
| –55°C to 125°C | TVSOP – DGV | Tape and reel | SN74AHC174DGV | HA174 |
| | CDIP – J | Tube | SNJ54AHC174J | SNJ54AHC174J |
| | CFP – W | Tube | SNJ54AHC174W | SNJ54AHC174W |
| | LCCC – FK | Tube | SNJ54AHC174FK | SNJ54AHC174FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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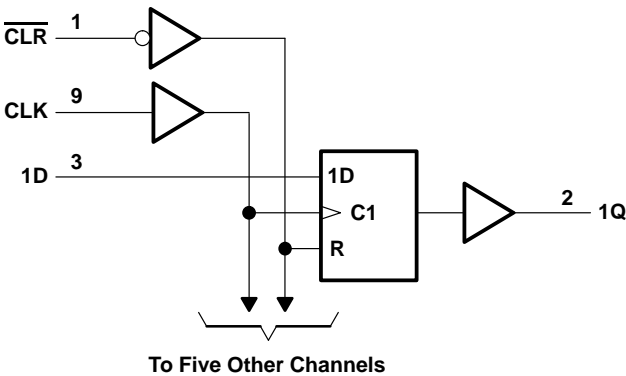
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FUNCTION TABLE

(each flip-flop)

| INPUTS | | | OUTPUT |
|-------------------------|------------|---|--------|
| $\overline{\text{CLR}}$ | CLK | D | Q |
| L | X | X | L |
| H | \uparrow | H | H |
| H | \uparrow | L | L |
| H | L | X | Q_0 |

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | –0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | –0.5 V to 7 V |
| Output voltage range, V_O (see Note 1) | –0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, I_{IK} ($V_I < 0$) | –20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ±20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ±25 mA |
| Continuous current through V_{CC} or GND | ±50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): | |
| D package | 73°C/W |
| DB package | 82°C/W |
| DGV package | 120°C/W |
| N package | 67°C/W |
| NS package | 64°C/W |
| PW package | 108°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54AHC174, SN74AHC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR

SCLS425F – JUNE 1998 – REVISED FEBRUARY 2002

recommended operating conditions (see Note 3)

| | | | SN54AHC174 | | SN74AHC174 | | UNIT |
|-----------------|------------------------------------|---------------------------------|------------|-----------------|------------|-----------------|------|
| | | | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | | 2 | 5.5 | 2 | 5.5 | V |
| V _{IH} | High-level input voltage | V _{CC} = 2 V | 1.5 | | 1.5 | | V |
| | | V _{CC} = 3 V | 2.1 | | 2.1 | | |
| | | V _{CC} = 5.5 V | 3.85 | | 3.85 | | |
| V _{IL} | Low-level input voltage | V _{CC} = 2 V | | 0.5 | | 0.5 | V |
| | | V _{CC} = 3 V | | 0.9 | | 0.9 | |
| | | V _{CC} = 5.5 V | | 1.65 | | 1.65 | |
| V _I | Input voltage | | 0 | 5.5 | 0 | 5.5 | V |
| V _O | Output voltage | | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 2 V | | –50 | | –50 | μA |
| | | V _{CC} = 3.3 V ± 0.3 V | | –4 | | –4 | mA |
| | | V _{CC} = 5 V ± 0.5 V | | –8 | | –8 | |
| I _{OL} | Low-level output current | V _{CC} = 2 V | | 50 | | 50 | μA |
| | | V _{CC} = 3.3 V ± 0.3 V | | 4 | | 4 | mA |
| | | V _{CC} = 5 V ± 0.5 V | | 8 | | 8 | |
| Δt/Δv | Input transition rise or fall rate | V _{CC} = 3.3 V ± 0.3 V | | 100 | | 100 | ns/V |
| | | V _{CC} = 5 V ± 0.5 V | | 20 | | 20 | |
| T _A | Operating free-air temperature | | –55 | 125 | –40 | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | SN54AHC174 | | SN74AHC174 | | UNIT |
|-----------------|---|-----------------|-----------------------|-----|-------|------------|------|------------|------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | I _{OH} = –50 μA | 2 V | 1.9 | 2 | | 1.9 | | 1.9 | | V |
| | | 3 V | 2.9 | 3 | | 2.9 | | 2.9 | | |
| | | 4.5 V | 4.4 | 4.5 | | 4.4 | | 4.4 | | |
| | I _{OH} = –4 mA | 3 V | 2.58 | | | 2.48 | | 2.48 | | |
| | I _{OH} = –8 mA | 4.5 V | 3.94 | | | 3.8 | | 3.8 | | |
| V _{OL} | I _{OL} = 50 μA | 2 V | | | 0.1 | | 0.1 | | 0.1 | V |
| | | 3 V | | | 0.1 | | 0.1 | | 0.1 | |
| | | 4.5 V | | | 0.1 | | 0.1 | | 0.1 | |
| | I _{OL} = 4 mA | 3 V | | | 0.36 | | 0.5 | | 0.44 | |
| | I _{OL} = 8 mA | 4.5 V | | | 0.36 | | 0.5 | | 0.44 | |
| I _I | V _I = 5.5 V or GND | 0 V to 5.5 V | | | ± 0.1 | | ± 1* | | ± 1 | μA |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | | 4 | | 40 | | 40 | μA |
| C _i | V _I = V _{CC} or GND | 5 V | | 1.7 | 10 | | | | 10 | pF |

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

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SN54AHC174, SN74AHC174

HEX D-TYPE FLIP-FLOPS

WITH CLEAR

SCLS425F – JUNE 1998 – REVISED FEBRUARY 2002

timing requirements over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted)

| | | | $T_A = 25^\circ\text{C}$ | | SN54AHC174 | | SN74AHC174 | | UNIT |
|----------|--|----------------------------------|--------------------------|-----|------------|-----|------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_w | Pulse duration | $\overline{\text{CLR}}$ low | 5 | | 5 | | 5 | | ns |
| | | CLK high or low | 5 | | 5 | | 5 | | |
| t_{su} | Setup time before $\text{CLK}\uparrow$ | Data | 5 | | 6 | | 6 | | ns |
| | | $\overline{\text{CLR}}$ inactive | 3 | | 3 | | 3 | | |
| t_h | Hold time, data after $\text{CLK}\uparrow$ | | 0 | | 0 | | 0 | | ns |

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted)

| | | | $T_A = 25^\circ\text{C}$ | | SN54AHC174 | | SN74AHC174 | | UNIT |
|----------|--|----------------------------------|--------------------------|-----|------------|-----|------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_w | Pulse duration | $\overline{\text{CLR}}$ low | 5 | | 5 | | 5 | | ns |
| | | CLK high or low | 5 | | 5 | | 5 | | |
| t_{su} | Setup time before $\text{CLK}\uparrow$ | Data | 4.5 | | 4.5 | | 4.5 | | ns |
| | | $\overline{\text{CLR}}$ inactive | 2.5 | | 2.5 | | 2.5 | | |
| t_h | Hold time, data after $\text{CLK}\uparrow$ | | 0.5 | | 0.5 | | 0.5 | | ns |

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | $T_A = 25^\circ\text{C}$ | | | SN54AHC174 | | SN74AHC174 | | UNIT |
|-------------|-------------------------|-------------|----------------------|--------------------------|------|-------|------------|-------|------------|------|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| f_{max} | | | $C_L = 15\text{ pF}$ | 95* | 170* | | 80* | | 80 | | MHz |
| | | | $C_L = 50\text{ pF}$ | 55 | 130 | | 50 | | 50 | | |
| t_{PHL} | $\overline{\text{CLR}}$ | Any Q | $C_L = 15\text{ pF}$ | | 4.5* | 11.4* | 1* | 13.5* | 1 | 13.5 | ns |
| t_{PLH} | CLK | Any Q | $C_L = 15\text{ pF}$ | | 5.8* | 11* | 1* | 13* | 1 | 13 | ns |
| t_{PHL} | | | | | 5.8* | 11* | 1* | 13* | 1 | 13 | |
| t_{PHL} | $\overline{\text{CLR}}$ | Any Q | $C_L = 50\text{ pF}$ | | 6 | 14.9 | 1 | 17 | 1 | 17 | ns |
| t_{PLH} | CLK | Any Q | $C_L = 50\text{ pF}$ | | 7.5 | 14.5 | 1 | 16.5 | 1 | 16.5 | ns |
| t_{PHL} | | | | | 7.5 | 14.5 | 1 | 16.5 | 1 | 16.5 | |
| $t_{sk(o)}$ | | | $C_L = 50\text{ pF}$ | | | 1.5** | | | | 1.5 | ns |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

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SCLS425F – JUNE 1998 – REVISED FEBRUARY 2002

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | $T_A = 25^\circ\text{C}$ | | | SN54AHC174 | | SN74AHC174 | | UNIT |
|--------------------|-------------------------|----------------|----------------------|--------------------------|------|------|------------|------|------------|------|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| f_{\max} | | | $C_L = 15\text{ pF}$ | 130* | 240* | | 110* | | 110 | | MHz |
| | | | $C_L = 50\text{ pF}$ | 90 | 180 | | 80 | | 80 | | |
| t_{PHL} | $\overline{\text{CLR}}$ | Any Q | $C_L = 15\text{ pF}$ | | 3* | 7.6* | 1* | 9* | 1 | 9 | ns |
| t_{PLH} | CLK | Any Q | $C_L = 15\text{ pF}$ | | 4.1* | 7.2* | 1* | 8.5* | 1 | 8.5 | ns |
| t_{PHL} | | | | | 4.1* | 7.2* | 1* | 8.5* | 1 | 8.5 | |
| t_{PHL} | $\overline{\text{CLR}}$ | Any Q | $C_L = 50\text{ pF}$ | | 4.2 | 9.6 | 1 | 11 | 1 | 11 | ns |
| t_{PLH} | CLK | Any Q | $C_L = 50\text{ pF}$ | | 5.5 | 9.2 | 1 | 10.5 | 1 | 10.5 | ns |
| t_{PHL} | | | | | 5.5 | 9.2 | 1 | 10.5 | 1 | 10.5 | |
| $t_{\text{sk(o)}}$ | | | $C_L = 50\text{ pF}$ | | | 1** | | | | 1 | ns |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

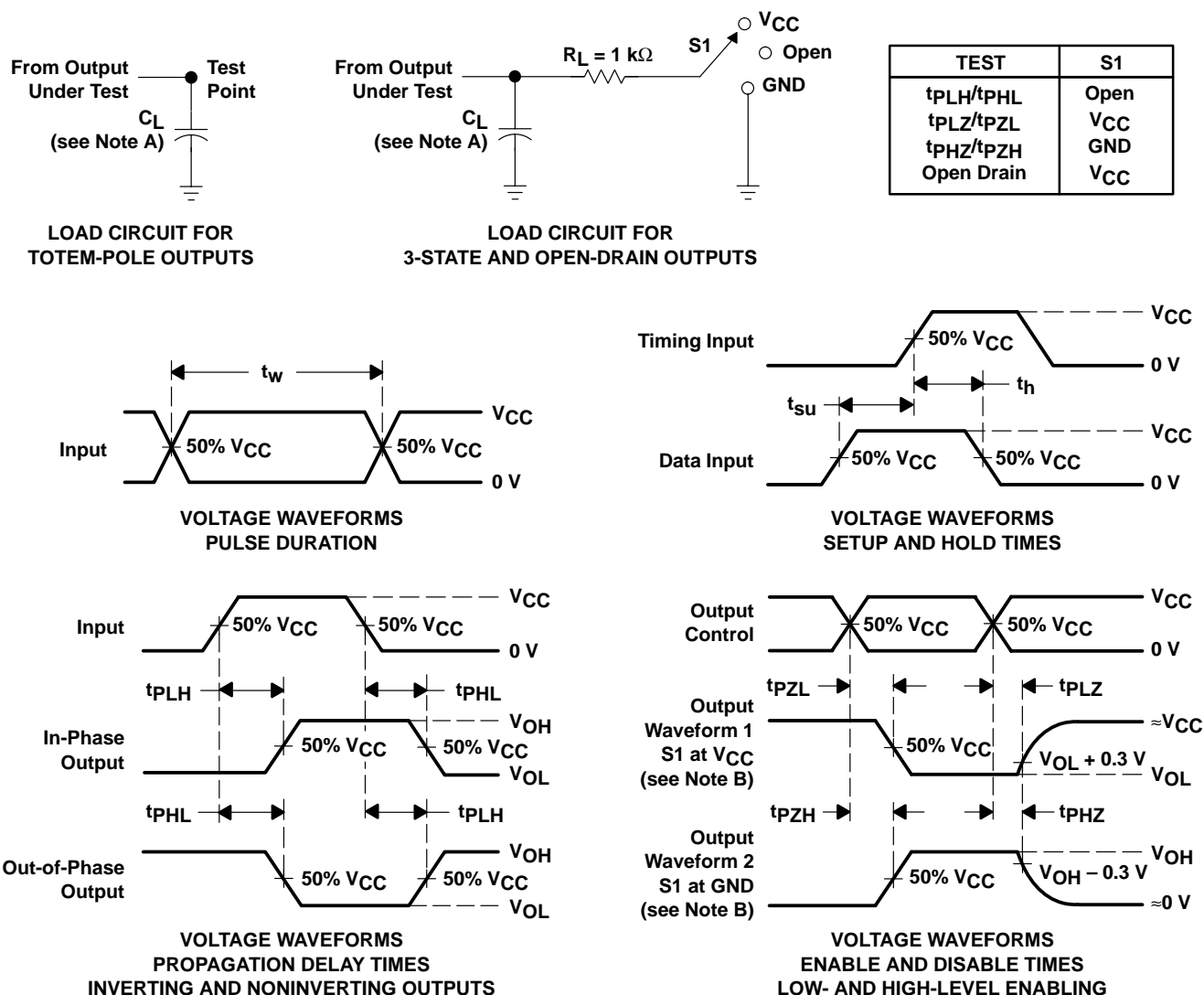
operating characteristics, $T_A = 25^\circ\text{C}$

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|---|-----------------------------|------|------|
| C_{pd} Power dissipation capacitance | No load, $f = 1\text{ MHz}$ | 15.2 | pF |

SN54AHC174, SN74AHC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR

SCLS425F – JUNE 1998 – REVISED FEBRUARY 2002

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74AHC174D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DBR | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DBRE4 | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DBRG4 | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DGVR | ACTIVE | TVSOP | DGV | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DGVRE4 | ACTIVE | TVSOP | DGV | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DGVRG4 | ACTIVE | TVSOP | DGV | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174DRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174N | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74AHC174NE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74AHC174NSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174NSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174NSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174PWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174PWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHC174PWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AHC174DBR | SSOP | DB | 16 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AHC174DGVR | TVSOP | DGV | 16 | 2000 | 330.0 | 12.4 | 6.8 | 4.0 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74AHC174DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74AHC174NSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AHC174PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 7.0 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AHC174DBR | SSOP | DB | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74AHC174DGVR | TVSOP | DGV | 16 | 2000 | 346.0 | 346.0 | 29.0 |
| SN74AHC174DR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74AHC174NSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74AHC174PWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

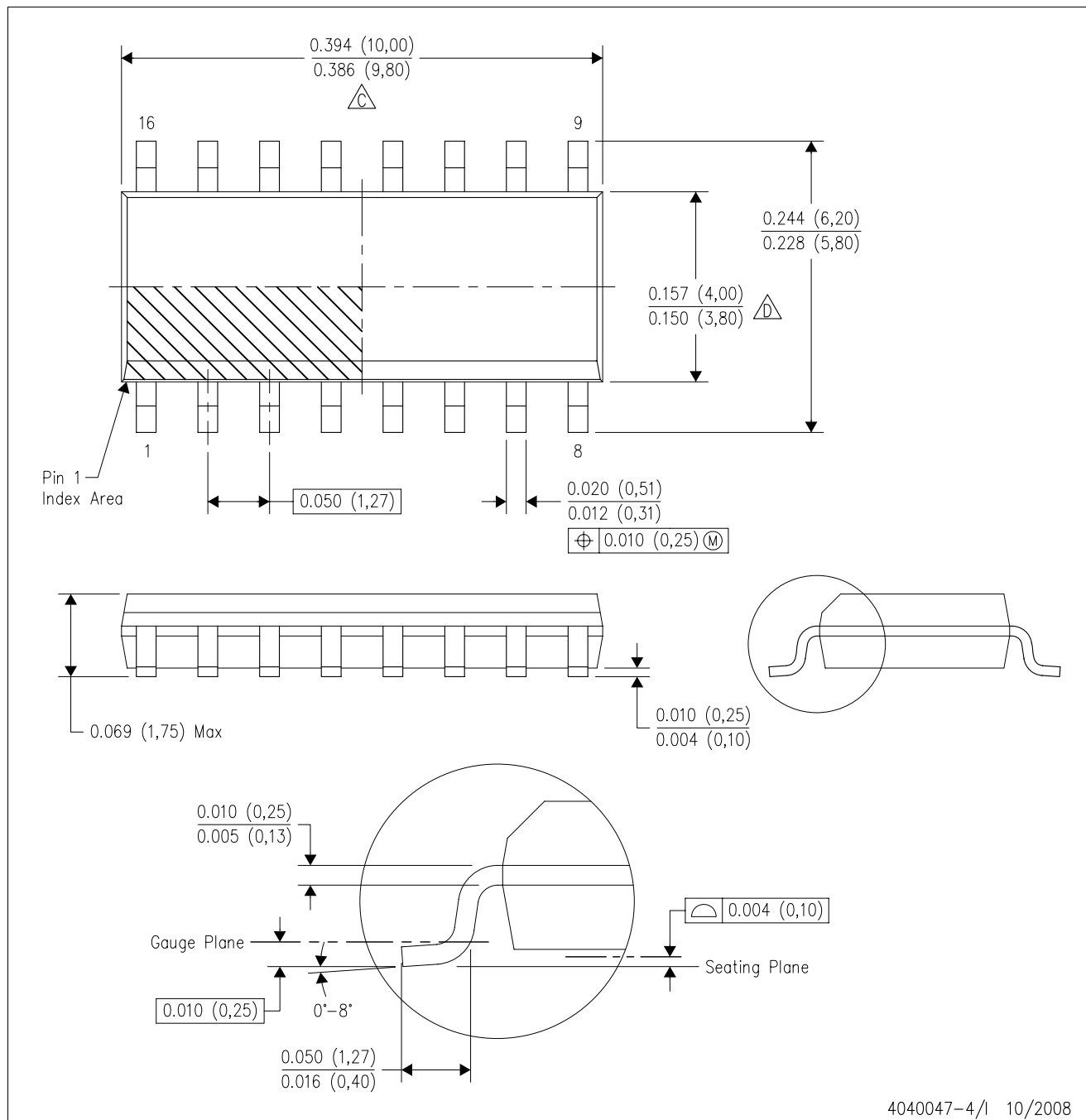
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/1 10/2008

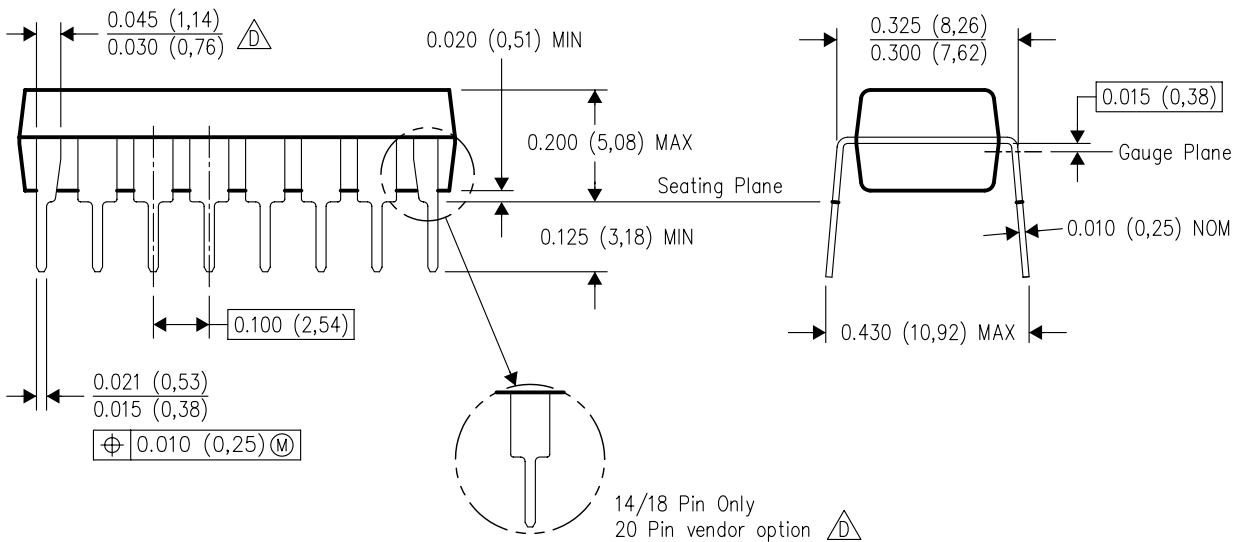
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



| PINS ** | 14 | 16 | 18 | 20 |
|---------------------|------------------|------------------|------------------|------------------|
| DIM | | | | |
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS-001 VARIATION | AA | BB | AC | AD |



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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